

Press Release 6/21/11

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RELEASE UPON RECEIPT

Santa Barbara, CA: Sikama International, Inc. has released their newest reflow solder/curing oven – the **Ultra Profile 1200**. The UP 1200 is a multi-purpose, continuous flow, reflow and curing oven capable of temperatures up to 400°C and atmosphere levels as low as 10ppm O₂.

The UP 1200 extends Sikama's offering of 300mm ovens with the addition of this bottom conduction, top convection oven. With eight (8) work zones internal to the oven: six (6) heat zones and two (2) cooling zones the oven is capable of a wide variety of processes.

This versatile oven can be used in solder reflow applications from 300mm 10um wafer bumping to 5kg microwave power modules as well as for epoxy curing. The ovens "Walking Beam" transport mechanism is designed to move even the heaviest of these work items from zone-to-zone through the oven with ease.

Sikama ovens are well known in the wafer bump industry and the factory has already received orders from two major wafer fabs and an LED chip manufacturer for this newest member of the Sikama lineup.

Incorporating Sikama's **Falcon ICS 412 Flux Coater** with the **Ultra Profile 1200** creates a system capable of processing 6" to 12" wafers (flux and reflow) in a multi-zone, in-line system with a small 1.2 meter x 5.7 meter footprint.

Be sure to visit us at SEMICON West, **Booth 6060**, July 12-14, 2011, Moscone Center in San Francisco.